

PMP20025 REV A Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
C17, C18	2	470uF	2TPE470MAJGB	Panasonic	CAP, Tantalum Polymer, 470 μ F, 2 V, +/- 20%, 0.011 ohm, 3.5x1.9x2.8mm SMD	3.5x1.9x2.8mm
C19, C20	2	22uF	C3216X5R1E226M160AB	TDK	CAP, CERM, 22 μ F, 25 V, +/- 20%, X5R, 1206_190	1206_190
C21, C22	2	47uF	GRM21BR61A476ME15	MuRata	CAP, CERM, 47 μ F, 10 V, +/- 20%, X5R, 0805	0805
C23, C24	2	DNP	GRM21BR61A476ME15	MuRata	CAP, CERM, 47 μ F, 10 V, +/- 20%, X5R, 0805	0805
C25	1	100uF	293D107X9020E2TE3	Vishay-Sprague	CAP, TA, 100uF, 20V, +/-10%, 0.5 ohm, SMD	7343-43
C26	1	DNP	GRM1555C1H102JA01D	MuRata	CAP, CERM, 1000 pF, 50 V, +/- 5%, COG/NPO, 0402	0402
C27	1	3300pF	GRM155R71H332KA01D	MuRata	CAP, CERM, 3300 pF, 50 V, +/- 10%, X7R, 0402	0402
J3, J4	2		OSTTE020161	On-Shore Technology	Terminal Block, 2x1, 3.5mm, TH	2x1 Terminal Block
L3, L4	2	1uH	DFE252012F-1R0M	Toko	Inductor, Shielded, 1 μ H, 3.3 A, 0.040 ohm	1008
Q2	1	25V	CSD16410Q5A	Texas Instruments	MOSFET, N-CH, 25 V, 59 A, SON 5x6mm	SON 5x6mm
R13	1	49.9	CRCW040249R9FKED	Vishay-Dale	RES, 49.9, 1%, 0.063 W, 0402	0402
R14	1	100k	CRCW0402100KFKED	Vishay-Dale	RES, 100 k, 1%, 0.063 W, 0402	0402
R15	1	475k	CRCW0402475KFKED	Vishay-Dale	RES, 475 k, 1%, 0.063 W, 0402	0402
R16	1	200k	CRCW0402200KFKED	Vishay-Dale	RES, 200 k, 1%, 0.063 W, 0402	0402
R17	1	10.0k	CRCW060310K0FKEA	Vishay-Dale	RES, 10.0 k, 1%, 0.1 W, 0603	0603
R18	1	0.032	WSL2512R0320FEA18	Vishay-Dale	RES, 0.032, 1%, 2 W, 2512	2512
TP7, TP8	2	Red	5000	Keystone	Test Point, Miniature, Red, TH	Red Miniature Testpoint
TP9, TP12	2	Black	5001	Keystone	Test Point, Miniature, Black, TH	Black Miniature Testpoint
TP10, TP11	2	White	5002	Keystone	Test Point, Miniature, White, TH	White Miniature Testpoint
U2	1		TPS62184YZFR	Texas Instruments	4-V to 17-V, 6-A, 2-Phase Step-Down Converter with AEE, YZF0024AMAM	YZF0024AMAM

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